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Atty. Dkt. No. 035905-0164 (MA-100-I)

***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

Applicant: S. Brad HERNER et al.  
Title: LOW-TEMPERATURE, LOW-  
RESISTIVITY HEAVILY  
DOPED P-TYPE POLYSILICON  
DEPOSITION  
Appl. No.: 10/769,047  
Filing Date: 1/30/2004  
Examiner: Chen, Bret P.  
Art Unit: 1792  
Confirmation Number: 7037

**AMENDMENT AND REPLY UNDER 37 CFR 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Non-Final Office Action dated November 1, 2007, concerning the above-referenced patent application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this document.

**Remarks/Arguments** begin on page 5 of this document.

Please amend the application as follows: